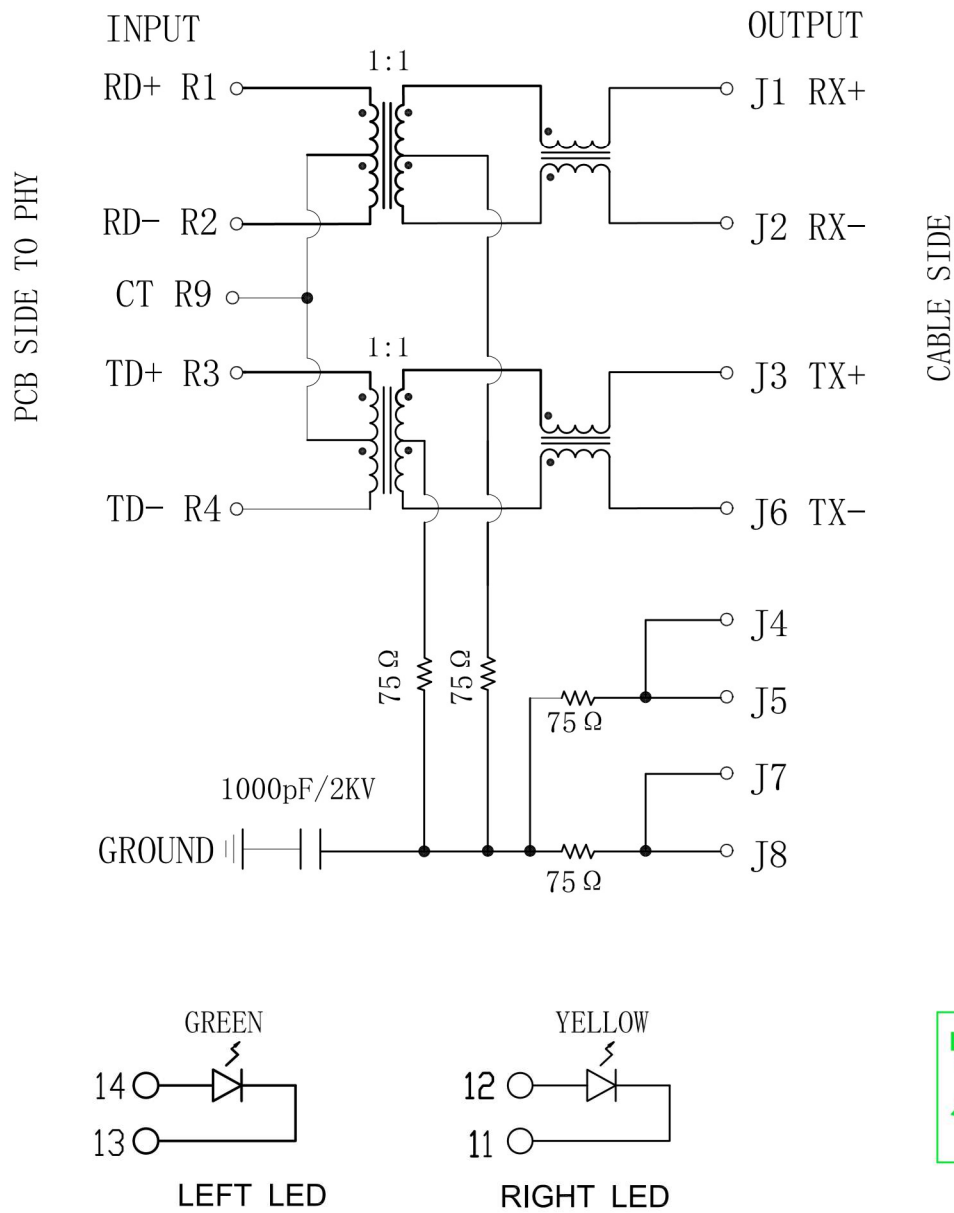


Schematic:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		24/12/2008	



Electrical Specifications:

- Transmitter filter & Receiver filter
Type:Balance low pass 100Ω impedance
Insertion Loss:
1-100MHz:-1.0dB MAX
Return Loss:
1-30MHz:-18dB MIN. load 100Ω
30-60MHz:-16dB MIN. load 100Ω
60-80MHz:-12dB MIN. load 100Ω
- Turns Ratio: TX=1:1 RX=1:1
- Inductance @ 100KHz, 0.1V, 8mA DC BIAS
Input (R1-R2), Input (R3-R4) :350uH MIN
- Crosstalk: 1-100MHz:-30dB MIN
- Common Mode Rejection: 1-100MHz:-30dB MIN
- Hipot:
Input (R1-R2) to Output (J1-J2) :1500VAC, 60sec
Input (R3-R4) to Output (J3-J6) :1500VAC, 60sec
Output (J1-J2), Output (J3-J6) to Shell:2500VAC, 5sec.
- Operating temperature: -40°C to +85°C.

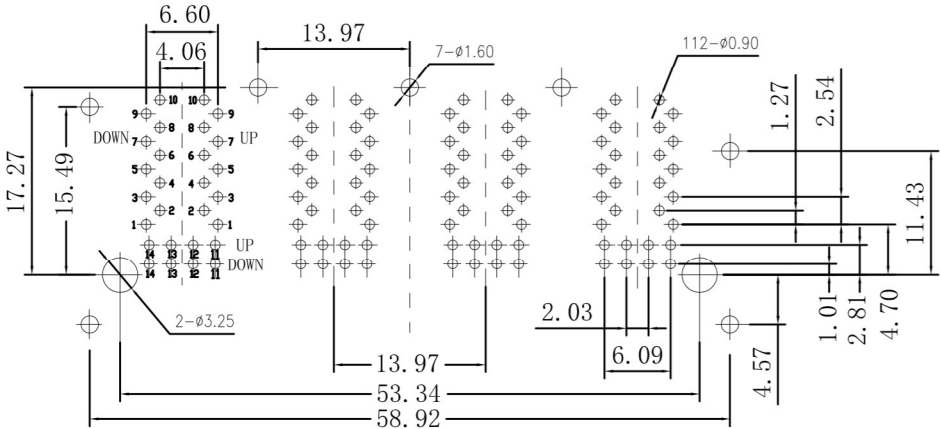
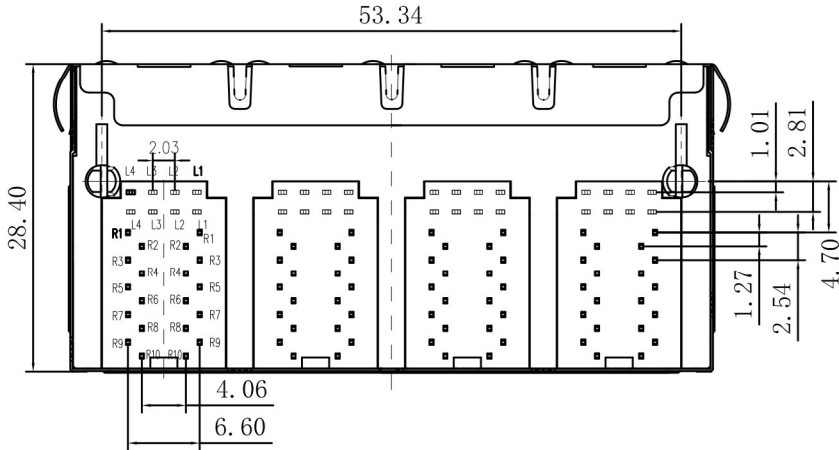
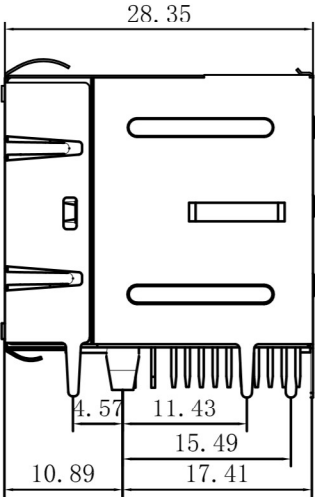
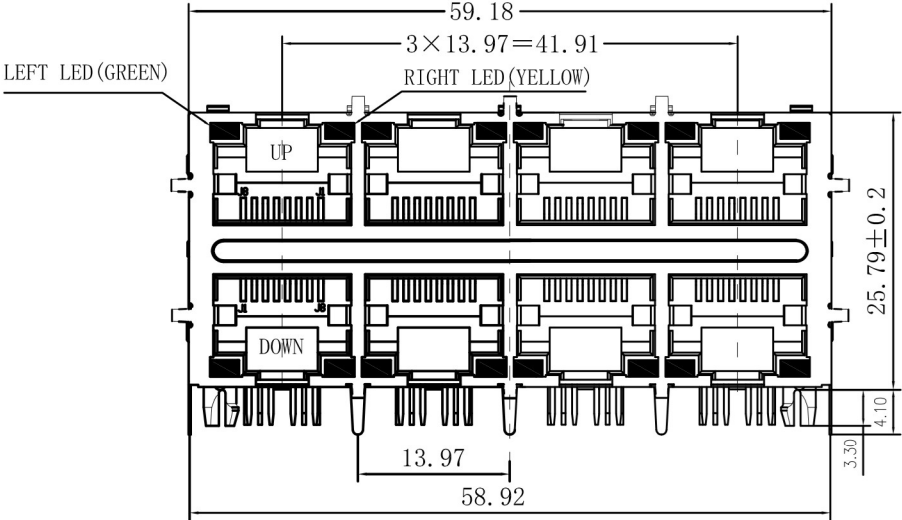
Emitting Color	λ p(nm)	VF@IF=20mA	IR @VR=5V
GREEN	565	1.8~2.6V	10 μA max
YELLOW	585	1.8~2.6V	10 μA max



X:X	±0.30	APPD:	Summit Electronics BV	
X:XX	±0.25	CHKD:		
X:XXX	±0.05	DR: TOM		
ANGLES	±1°	UNIT: mm	PART NO. : SRJ204010020	
		SCALE: 2/1	SHEET: 1/2	REV: A DWG NO. :

Mechanical :

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		24/12/2008	



NOTES:

1. Designed to support application, such as SOHO (ADSL modems), LAN-on-Motherboard (LOM), hub and Switches.
2. Meets IEEE 802.3 specification
3. Connector Materials:
Housing: Thermoplastic UL94V-0
Contact/Shield: Copper alloy
Shield plating: Nickel
Contact plating: Gold 6 micro-inches min. In contact area.
4. Wave solder tip temperature: 265°C Max, 5 Sec Max.



SUGGESTED PCB LAYOUT (TOP VIEW)

X:X	±0.30	APPD:	Summit Electronics BV	
X:XX	±0.25	CHKD:		
X:XXX	±0.05	DR: TOM	TITLE: RJ45 .Transformer. 10/100 Base-T W/LED. 2×4	
ANGLES	±1°	UNIT: mm	PART NO. : SRJ204010020	
		SCALE: 2/1	SHEET: 2/2	REV: A DWG NO. : LP08122405